IN THE CLAIMS

Please cancel claims 13-30. Attached is a listing of the current claims.

1. (original) An electroless plating solution comprising:

a primary metal selected from cobalt, rhodium, iridium, nickel, palladium, platinum, copper, silver, gold, and combinations thereof;

at least one primary reducing agent;

a complexing and buffering agent consisting essentially of a single agent;

at least one pH adjusting agent;

optionally at least one surface active agent; and

the solution, reaction, and mixture products thereof.

2. (original) The solution according to claim 1, wherein primary metal is in a concentration from about 5 gram/liter to about 35 gram/liter.

3. (original) The solution according to claim 1, further including:

a secondary metal selected from chromium, molybdenum, tungsten, manganese, technetium, rhenium, and combinations thereof.

4. (original) The solution according to claim 1, further including:

a secondary metal selected from chromium, molybdenum, tungsten, manganese, technetium, rhenium, and combinations thereof; and wherein

secondary metal is in a concentration from about 1 gram/liter to about 30 gram/liter.

5. (original) The composition according to claim 1, wherein the primary reducing agent includes:

a boron-containing compound in a concentration range from about 2 gram/liter to about 30 gram/liter; and further including:

a secondary reducing agent in a concentration range from about 0 gram/liter to about 2 gram/liter.

6. (original) The composition according to claim 1, wherein the primary reducing agent includes:

a boron-containing compound in a concentration range from about 2 gram/liter to about 30 gram/liter, wherein the boron-containing compound is selected from dimethylaminoborane, diethylaminoborane, morpholine borane, and mixtures thereof; and further including:

a secondary reducing agent in a concentration range from about 0 gram/liter to about 2 gram/liter.

7. (original) The composition according to claim 1, wherein the primary reducing agent includes:

a boron-containing compound in a concentration range from about 2 gram/liter to about 30 gram/liter, wherein the boron-containing compound is

selected from dimethylaminoborane, diethylaminoborane, morpholine borane, and mixtures thereof; and further including:

a secondary reducing agent in a concentration range from about 0 gram/liter to about 2 gram/liter, wherein the secondary reducing agent is selected from ammonium hypophosphite, hypophosphites of lithium, sodium, and potassium, hypophosphites of, magnesium, calcium, and strontium, nickel hypophosphite, hypophosphorous acid, sulfites, bisulfites, hydrosulfites, metabisulfites, dithionates, tetrathionates, thiosulfates, thioureas, hydrazines, hydroxylamines, aldehydes, glyoxylic acid, reducing sugars diisobutylaluminum hydride, and sodium bis(2-methoxyethoxy)aluminum hydride.

8. (original) The composition according to claim 1, wherein the complexing and buffering agent includes $(NH_2)SO_4$.

9. (original) The composition according to claim 1, wherein the complexing and buffering agent includes $(NH_2)SO_4$ in a concentration range from about 80 gram/liter to about 600 gram/liter.

10. (original) The composition according to claim 1, wherein the at least one pH adjusting agent includes tetramethylammonium hydroxide in a concentration range from about 30 mL to about 150 mL.

11. (original) The composition according to claim 1, wherein the composition is in a pH range from about pH 7 to about pH 10.

12. (original) The composition according to claim 1, wherein the composition is in a temperature range from about 20° C to about 60° C.